Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **F-0203-04** DATE: 2/27/2002
Product Affected: Plastic Ball Grid Array (PBGA) BG121

Date Effective: 5/27/2002

MEANS OF DISTINGUISHING CHANGED DEVICES:
- ☐ Product Mark
- ☐ Back Mark
- ☐ Date Code
- ■ Other — Alpha suffix "E" in assembly lot number

Contact: Geoffrey Cortes
Title: Manager, Corporate Quality & Reliability
Phone #: (408) 492-8321
Fax #: (408) 727-2328
E-mail: gcortes@idt.com

Attachment:: ■ Yes ☐ No

Samples: Availble upon request

DESCRIPTION AND PURPOSE OF CHANGE:
- ☐ Die Technology
- ☐ Wafer Fabrication Process
- ■ Assembly Process
- ☐ Equipment
- ☐ Material
- ☐ Testing
- ☐ Manufacturing Site
- ☐ Data Sheet
- ☐ Other

To implement auto mold process. The mold thickness will change from 1.17 mm to 0.80 mm. Please see attachment #1 for additional details.

RELIABILITY/QUALIFICATION SUMMARY:

The qualification testing will verify that there is no change to the product reliability.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.
IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: ____________________ ☐ ***Approval for shipments prior to effective date.***

Name/Date: ____________________ E-Mail Address: ____________________

Title: ____________________ Phone# /Fax# : ____________________

CUSTOMER COMMENTS: ____________________

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: ____________________ DATE: ____________________

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ATTACHMENT - PCN #: F-0203-04

PCN Type: To implement auto mold process

Data Sheet Change: N/A

Detail of Change: The auto mold proces is being implemented to improve the product manufacturability by reducing the process cycle time. This change will have the following impact on the package dimension:

DESCRIPTION	FROM	TO
Mold Cap Thickness	1.17 mm	0.80 mm
Package Thickness	2.13 mm	1.81 mm

Conversion schedule (Estimated)

	Sample Availability	Production Shipments
BG121	Availble	5/3/2002

Please contact your local field sales representative for sample availability and production shipments.

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ATTACHMENT - PCN #: F-0203-04

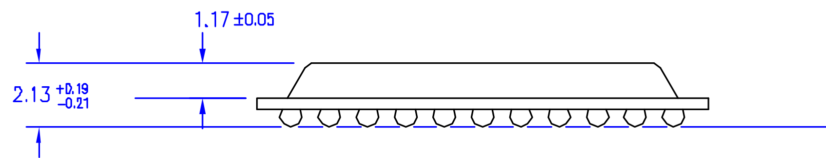
Qualification Plan: **P01-03-06** **Expected Completion Date:** **4/26/2002**

Test Vehicle: 72825LB15BG

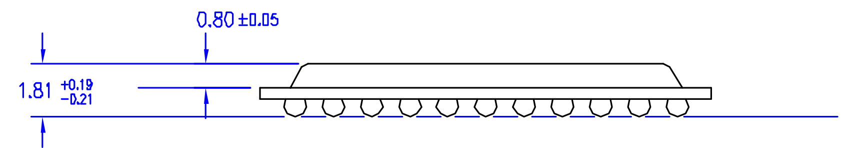
Test Description Condition	Test Methods	Sample Size / # Fails	Test Results
Highly Accelerated Stress Test (HAST) (100 Hrs, @130°C/85%RH,Static Bias)	EIA/JESD22-A110	45/0	
Temperature Cycling (-65°C to +150°C, 500 cyc)	MIL-STD-883 Method 1010	45/0	
Auto Clave (SPP) (168Hrs, @ 2ATM, 121°C)	EIA/JESD22-A102	45/0	
Package Moisture Characterization	JEDEC J-STD-20	22/0	
Internal Visual Inspection	MIL-STD-883 Method 2010	5/0	
External Visual Inspection	MIL-STD-883 Method 2009	25/0	
S.A.T	JEDEC J-STD-35	10/0	
X-ray Examination	Per IDT specification	45/0	
Bond Pull Test	MIL-STD-883 Method 2011	5/0	
Bake & Ball Shear Test	EIA/JESD22-B116	5/0	
Physical Dimension	MIL-STD-883 Method 2016	5/0	
Solder Ball Shear	JESD22-B117	3/0	
Resistance to Solvents	MIL-STD-883 Method 2015	5/0	

BG121

FROM:



TO:



ALL DIMENSIONS IN MM